



1/f 2826

**PATENT APPLICATION**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of

Docket No: Q65847

Tadaaki HARADA, *et al.*

Appln. No.: 09/914,363

Group Art Unit: 2826

Confirmation No.: 3899

Examiner: Leonardo ANDUJAR

Filed: August 27, 2001

For: RESIN COMPOSITION FOR SEMICONDUCTOR ENCAPSULATION,  
SEMICONDUCTOR DEVICE COMPRISING THE SAME AND PROCESS FOR THE  
PRODUCTION OF SEMICONDUCTOR DEVICE USING THE SAME

**RESPONSE UNDER 37 C.F.R. § 1.111**

**MAIL STOP AMENDMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

Please consider the remarks below in response to the Action mailed February 9, 2005.

Claims 1-22 are all the claims pending in the application. Claims 7-21 are withdrawn from consideration for being drawn to a non-elected invention.

Applicants note with appreciation the Examiner's indication of allowable subject matter at Section No. 7 (page 4) of the Office Action.

Referring to Section Nos. 4-6 at pages 2 and 3 of the Office Action, Claims 1-4 are rejected under 35 U.S.C. § 103(a) as being unpatentable over JP 2-147618 ("JP '618").

Applicants respectfully traverse. JP '618 does not teach or suggest each and every element of the claimed resin composition.

Claim 1 is drawn to a resin composition for semiconductor encapsulation. The resin composition comprises components (A) to (D), as particularly recited in Claim 1, and has a viscosity of 7,000 poise or more at 25°C and 5,000 poise or less at 80°C. Component (B) of